Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	25019	semiconductor and ((connect$3 or contact$3) adj pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/25 16:55
L2	11976	1 and (hole or recess$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/25 16:55
L3	9796	2 and (interconnect$3 or wir$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/25 16:56
L4	7851	3 and (insulat$3 or dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/25 16:57
L5	1037	4 and bump and encapsulat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/25 16:57